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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/013,103	11/06/2001	Krishna Seshan	42390P5778D	1577
8791	7590 09/16/2003			
BLAKELY SOKOLOFF TAYLOR & ZAFMAN			EXAMINER	
12400 WILSHIRE BOULEVARD, SEVENTH FI LOS ANGELES, CA 90025		ENTH FLOOR	LEWIS, MONICA	
			ART UNIT	PAPER NUMBER
	•		0000	

DATE MAILED: 09/16/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)				
	10/013,103	SESHAN ET AL.				
Office Action Summary	Examin r	Art Unit	_			
	Monica Lewis	2822				
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet w	ith the correspondenc address				
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period was period to reply within the set or extended period for reply will, by statute, - Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).  Status	36(a). In no event, however, may a or within the statutory minimum of thi vill apply and will expire SIX (6) MOI or cause the application to become A	reply be timely filed ty (30) days will be considered timely. NTHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).				
1) Responsive to communication(s) filed on <u>07 J</u>	<u>luly 2003</u> .					
2a) This action is <b>FINAL</b> . 2b) ☐ Th	is action is non-final.					
3) Since this application is in condition for alloward closed in accordance with the practice under Disposition of Claims						
4) ☐ Claim(s) <u>17-24</u> is/are pending in the application	ın.					
4a) Of the above claim(s) is/are withdraw						
5) Claim(s) is/are allowed.	With the third consideration.					
6)⊠ Claim(s) <u>17-24</u> is/are rejected.						
7) Claim(s) is/are objected to.						
8) Claim(s) are subject to restriction and/o	r election requirement.					
Application Papers	. 0,00					
9) The specification is objected to by the Examine	r.	,				
10)⊠ The drawing(s) filed on 06 November 2001 is/a	re: a)⊠ accepted or b)□ c	bjected to by the Examiner.				
Applicant may not request that any objection to the	e drawing(s) be held in abey	ance. See 37 CFR 1.85(a).				
11)☐ The proposed drawing correction filed on	_ is: a)□ approved b)□ o	lisapproved by the Examiner.				
If approved, corrected drawings are required in rep	oly to this Office action.					
12)☐ The oath or declaration is objected to by the Ex	aminer.					
Priority under 35 U.S.C. §§ 119 and 120						
13)☐ Acknowledgment is made of a claim for foreign	priority under 35 U.S.C.	§ 119(a)-(d) or (f).				
a)☐ All b)☐ Some * c)☐ None of:						
<ol> <li>Certified copies of the priority documents have been received.</li> </ol>						
2. Certified copies of the priority documents have been received in Application No						
<ul> <li>3. Copies of the certified copies of the prior</li> <li>application from the International But</li> <li>* See the attached detailed Office action for a list</li> </ul>	reau (PCT Rule 17.2(a)).					
14)☐ Acknowledgment is made of a claim for domesti	c priority under 35 U.S.C.	§ 119(e) (to a provisional application).				
<ul> <li>a) ☐ The translation of the foreign language pro</li> <li>15)☐ Acknowledgment is made of a claim for domesting</li> </ul>	* *					
Attachment(s)	-					
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice of	Summary (PTO-413) Paper No(s) Informal Patent Application (PTO-152) .				

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#### **DETAILED ACTION**

1. This action is in response to the request for continued examination filed July 7, 2003.

#### Response to Arguments

2. Applicant's arguments with respect to claims 17-24 have been considered but are moot in view of the new ground(s) of rejection.

## Specification

3. The lengthy specification has not been checked to the extent necessary to determine the presence of all possible minor errors. Applicant's cooperation is requested in correcting any errors of which applicant may become aware in the specification.

### Claim Rejections - 35 USC § 102

4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 5. Claims 17, 18 and 21 are rejected under 35 U.S.C. 102(b) as being anticipated by Bacchetta et al. (U.S. Patent No. 5,795,821).

In regards to claim 17, Bacchetta et al. ("Bacchetta") discloses the following:

- a) an oxide layer (1) (For Example: See Figure 1);
- b) an adhesion layer (2) formed on said oxide layer (For Example: See Figure 1); and
- c) a first passivation layer (3) formed on said adhesion layer, said first passivation layer and said adhesion layer including at least one common chemical element (For Example: See Figure 1).

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In regards to claim 18, Bacchetta discloses the following:

a) a second passivation layer (5) formed upon said first passivation layer (For Example: See Figure 1).

In regards to claim 21, Bacchetta discloses the following:

a) first passivation layer includes silicon nitride (Si<sub>3</sub>N<sub>4</sub>) (For Example: See Column 4 Lines 1 and 2).

## Claim Rejections - 35 USC § 103

- 6. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 7. Claim 19 is rejected under 35 U.S.C. 103(a) as obvious over Bacchetta et al. (U.S. Patent No. 5,795,821) in view of Yu et al. (U.S. Patent No. 5,795,833).

In regards to claim 19, Bacchetta discloses the following:

a) oxide layer includes silicon dioxide (SiO<sub>2</sub>).

However, Yu et al. ("Yu") discloses a silicon oxide layer (For Example: See Figure 2). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Bacchetta to include a silicon oxide layer formed as disclosed in Yu because it aids in providing a good moisture barrier (For Example: See Column 2 Lines 38-42).

Additionally, since Bacchetta and Yu are both from the same field of endeavor, the purpose disclosed by Yu would have been recognized in the pertinent art of Bacchetta.

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8. Claim 20 is rejected under 35 U.S.C. 103(a) as obvious over Bacchetta et al. (U.S. Patent No. 5,795,821) in view of Oshika et al. (Japanese Patent No. 361292964).

In regards to claim 20, Bacchetta discloses the following:

a) adhesion layer includes silicon oxynitride.

However, Oshika et al. ("Oshika") discloses a silicon oxynitride layer (For Example: See Abstract). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Bacchetta to include a silicon oxynitride layer formed as disclosed in Oshika because it aids in relaxing thermal stress (For Example: See Abstract).

Additionally, since Bacchetta and Oshika are both from the same field of endeavor, the purpose disclosed by Yu would have been recognized in the pertinent art of Bacchetta.

9. Claim 22 is rejected under 35 U.S.C. 103(a) as obvious over Bacchetta et al. (U.S. Patent No. 5,795,821) in view of Fu et al. (U.S. Patent No. 5,807,787).

In regards to claim 22, Bacchetta fails to disclose the following:

a) second passivation layer includes polyimide.

However, Fu et al. ("Fu") discloses a polyimide layer (For Example: See Column 5 Lines 32-40). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Bacchetta to include a polyimide layer as disclosed in Fu because it aids in providing electrical insulation (For Example: See Column 5 Lines 32-40).

Additionally, since Bacchetta and Fu are both from the same field of endeavor, the purpose disclosed by Fu would have been recognized in the pertinent art of Bacchetta.

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10. Claim 23 is rejected under 35 U.S.C. 103(a) as obvious over Fujitsu (Japanese Patent No. 5511335) in view of Argos, Jr. et al. (U.S. Patent No. 5,483,023).

In regards to claim 23, Fujitsu discloses the following:

- a) a silicon dioxide insulating layer (For Example: See Abstract); and
- b) a silicon oxynitride adhesion layer formed on said silicon dioxide insulating layer (For Example: See Abstract).

In regards to claim 23, Fujitsu fails to disclose the following:

a) a silicon nitride hard passivation layer formed on said silicon oxynitride adhesion layer.

However, Argos, Jr. et al. ("Argos") discloses a silicon nitride layer (For Example: See Abstract). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Bacchetta to include a silicon nitride layer as disclosed in Argos because it aids in preventing contamination (For Example: See Abstract).

Additionally, since Fujitsu and Argos are both from the same field of endeavor, the purpose disclosed by Argos would have been recognized in the pertinent art of Fujitsu.

11. Claim 24 is rejected under 35 U.S.C. 103(a) as obvious over Fujitsu (Japanese Patent No. 55113335) in view of Argos, Jr. et al. (U.S. Patent No. 5,483,023) and Bryant et al. (U.S. Patent No. 5,698,456).

In regards to claim 24, Bacchetta fails to disclose the following:

a) photodefinable polyimide soft passivation layer formed on said silicon nitride hard passivation layer.

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However, Bryant discloses a polyimide layer (34) formed on silicon nitride (See

Figure 4e). It would have been obvious to one having ordinary skill in the art at the time the

invention was made to modify the semiconductor device of Bacchetta to include a polyimide

layer as disclosed in Bryant because it aids in protecting the device (See Column 5

Lines 6 and 7).

Additionally, since Fujitsu and Bryant are both from the same field of endeavor, the purpose

disclosed by Bryant would have been recognized in the pertinent art of Fujitsu.

Conclusion

Any inquiry concerning this communication or earlier communications from the 12.

examiner should be directed to Monica Lewis whose telephone number is 703-305-3743.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir

Zarabian can be reached on 703-308-4905. The fax phone number for the organization where

this application or proceeding is assigned is 703-308-7722 for regular and after final

communications. Any inquiry of a general nature or relating to the status of this application or

proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

ML

September 4, 2003

SUPERVISORY PATENT EXAMINER **TECHNOLOGY CENTER 2800**